

# System On Package: Miniaturization Of The Entire System By Rao Tummala

**By Rao Tummala**

Our CM300 on-wafer probe station was part of the technology used to advance System-in-Package (SiP) miniaturization efforts in automobiles and industrial and

System-on-Package (SOP) is an emerging microelectronic technology that places an entire system on a single chip-size package. Dr. Rao Tummala

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Introduction to System-on-package (SOP), Miniaturization of the entire system, Rao R. Tummala, Madhavan Swaminathan, McGraw-Hill, ISBN No. 978-0-07-145906-8

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Pris 1041 kr. K p System on Package (9780071459068) av Rao System on Package Miniaturization of the Entire System. Rao Tummala is a Chair professor

Can we miniaturize the entire system for better System miniaturization allows disruptive "Prof. Rao R. Tummala in ECE" is the property of its rightful owner.

miniaturization [ min ch r z sh n] (electronics) Reduction in the size and weight of a system, package, or component by using small parts arranged

Xpeedic s SiP design service enables customers to achieve system miniaturization by integrating ICs from different process into one package.

System on Package Miniaturization of the Entire System By: Rao Tummala. Pub Date . April 15, Optical System Design,

Rao Tummala, V. M. Published by Intext Educational Publishers. ISBN 10: 0700224378 ISBN 13: 9780700224371. Used Hardcover. Quantity Available: 1.

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